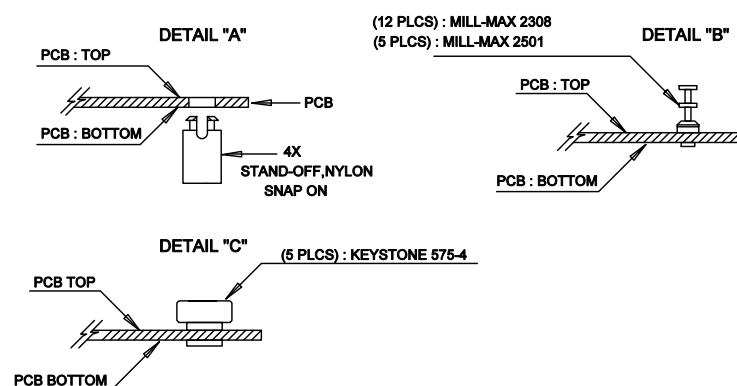
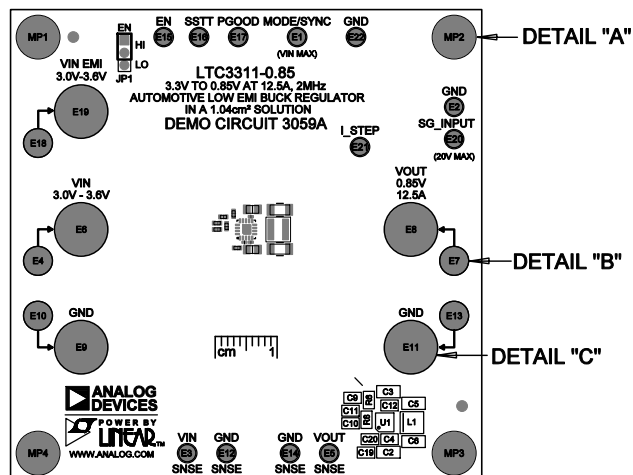


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	03	PRODUCTION	WL	09-27-21

## NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY REFLOW PROFILE SHALL BE IN ACCORDANCE WITH J-STD-020 WITH MAXIMUM SOLDER TEMPERATURE OF 250 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS  
LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.  
MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. APPLY ASSEMBLY STAMP OR QA STAMP TO BOTTOM OF BOARD (UNSHOWY AREA).
7. INSTALL TURRETS, STAND-OFFS AS SHOWN BELOW:
8. APPLY DEMO S/N AT AREA ON BOTTOM SIDE AS SHOWN ON SHEET 2.



APPROVALS		ANALOG DEVICES   POWER BY LINEAR	
PCB DES	NC	FOR ADI CUSTOMER USE ONLY	
APP ENG	WL	TITLE: TOP ASSEMBLY DRAWING 3.3V TO 0.85V AT 12.5A, 2MHz AUTOMOTIVE LOW EMI BUCK REGULATOR IN A 1.04cm <sup>2</sup> SOLUTION	
		SIZE	IC NO.
		N/A	LTC3311-0.85 DEMO CIRCUIT 3059A
		REV.	03
SCALE = NONE		SHT 1 OF 1	